

AMENDMENTS TO THE CLAIMS

Claims 1-5 (Cancelled).

6. (Previously Presented) A method of manufacturing a semiconductor element-mounting board, comprising:

arranging a plurality of conductive members in a mold;

injecting an electrically insulating resin material into the mold after the conductive members are arranged therein so that the conductive members and the resin material are integrally molded to form a base member having a semiconductor element-mounting face and a circuit board-mounting face opposite the semiconductor element-mounting face, said arranging of the conductive members comprising orienting the conductive members in the mold so that the conductive members are substantially orthogonal to the semiconductor element-mounting face and the circuit board-mounting face and extend linearly through an interior of the base member between the semiconductor element-mounting face and the circuit board-mounting face, said injecting comprising injecting the resin material in an axial direction parallel to the longitudinal axes of the conductive members through at least two injection openings arranged symmetrically around each of the conductive members;

mounting and electrically connecting a semiconductor element to the semiconductor element-mounting face by flip-chip mounting; and

mounting and electrically connecting the circuit board-mounting face to a circuit board.

7. (Previously Presented) A method of manufacturing a semiconductor element-mounting board, comprising:

arranging a plurality of conductive members in a mold;

injecting an electrically insulating resin material into the mold after the conductive members are arranged therein so that the conductive members and the resin material are integrally molded to form a base member having a semiconductor element-mounting face and a circuit board-mounting face opposite the semiconductor element-mounting face, said arranging

of the conductive members comprising orienting the conductive members in the mold so that the conductive members are substantially orthogonal to the semiconductor element-mounting face and the circuit board-mounting face and extend linearly through an interior of the base member between the semiconductor element-mounting face and the circuit board-mounting face, said injecting comprising injecting the resin material in an axial direction parallel to the longitudinal axes of the conductive members through at least two injection openings arranged symmetrically with respect to the conductive members, wherein the mold includes a first holding plate for holding a first axial end of each of the conductive members, the injection openings being formed in the first holding plate, includes a second holding plate for holding a second axial end of each of the conductive members and being operable to move in the axial direction, and includes a pressure regulation mechanism for biasing the second holding plate in the axial direction in response to a compression or extension of the conductive members due to said injection of the resin material;

during said injecting of the resin material, moving the second holding plate in the axial direction using the pressure regulation mechanism in response to the compression/extension of the conductive members due to said injection of the resin material, thereby restricting bends in the conductive members;

mounting and electrically connecting a semiconductor element to the semiconductor element-mounting face by flip-chip mounting; and

mounting and electrically connecting the circuit board-mounting face to a circuit board.

8. (Previously Presented) The method of claim 6, wherein said injecting comprises injecting the resin material in an axial direction parallel to the longitudinal axes of the conductive members through the injection openings formed in an end of the mold closest to and supporting a first end of each of the conductive members.

Claim 9 (Cancelled).

10. (Previously Presented) A method of manufacturing a semiconductor element-mounting board, comprising:

arranging a plurality of conductive members in a mold;

injecting an electrically insulating resin material into the mold after the conductive members are arranged therein so that the conductive members and the resin material are integrally molded to form a base member having a semiconductor element-mounting face and a circuit board-mounting face opposite the semiconductor element-mounting face, said arranging of the conductive members comprising orienting the conductive members in the mold so that the conductive members are substantially orthogonal to the semiconductor element-mounting face and the circuit board-mounting face and extend linearly through an interior of the base member between the semiconductor element-mounting face and the circuit board-mounting face;

after said injecting of the resin material, forming a projecting portion of the conductive member projecting from the circuit board-mounting face of the base member, said forming of the projecting portion including:

leveling the base member including the conductive members so that a thickness of the base member is equal to a length of each of the conductive members; and

after said leveling, removing only a portion of the resin material of the base member in a thickness direction of base member;

plastically deforming the projecting portion so as to form a land to be connected to a circuit board;

mounting and electrically connecting a semiconductor element to the semiconductor element-mounting face by flip-chip mounting; and

mounting and electrically connecting the circuit board-mounting face to a circuit board.

11. (Original) The method of claim 10, wherein said removing of the portion of the resin material comprises one of wet etching, dry etching, sandblasting, and machining.

Claims 12-18 (Cancelled).